



## LTM4608 68LD 15mm X 9mm X 2.82mm (TABLE OF MATERIAL DECLARATION)

*The LTM4608 is RoHS compliant per EU RoHS Directive 2003/95/EC.*

It contains less than 100ppm cadmium (Cd) and less than 1,000ppm of each - lead (Pb), mercury (Hg), hexavalent chromium (Cr+), polybrominated biphenyl (PBB) and polybrominated diphenyl ether (PBDE)

No.	Part Name	Material Name	Component Weight (gram)	Materials Analysis (element)	CAS Number	Material Mass (gram)	Materials Analysis (weight %)
1	Substrate	Circuit Board	0.212460	Barium Compounds	7727-43-7	0.00319	1.5
				Filler Substances (Silica Crystalline)	-	0.0848	39.91457
				Copper Metal	7440-50-8	0.11897	56
				Copper Compounds	1328-53-6	0.00004	0.018
				Ecotoxic substances	7439-92-1	0	0.00043
				Gold metal or alloy	7440-57-5	0.00098	0.46
				Nickel	7440-02-0	0.00446	2.1
2	Solder Paste	Alloy	0.035700	Zinc	7440-66-6	0.00002	0.007
				Sn	7440-31-5	0.03392	95.0
3	Passive/Active Components		0.281792	Sb	7440-36-0	0.00179	5.0
				Capacitor	-	0.04536	16.10
				Resistor	-	0.00505	1.79
				Inductor	-	0.22730	80.66
4	Active Ics	Silicon	0.102830	Diode	-	0.00408	1.45
				Silicon	7440-21-3	0.10283	100
5	Wire	Gold	0.002700	Au	7440-57-5	0.0027000	100
6	Encapsulation	Epoxy Resin	0.720670	Fused Silica	60676-86-0	0.55636	77.2
				Epoxy Resin	-	0.06414	8.9
				Phenol Resin	-	0.06414	8.9
				Crystalline Silica	14808-60-7	0.02162	3.0
				Carbon Black	1333-86-4	0.00360	0.5
				Metal Hydroxide	-	0.01081	1.5
<b>Total Package Weight</b>			<b>1.356152</b>				

Note: Composition derived from MSDS and material C of C from Vendors  
Component Weight based on assembly of generic parts